

# **Product Compliance Declaration**

Please see <a href="https://www.molex.com">www.molex.com</a> for the most up-to-date information.

### **Contact Information**

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

## **Part Information**

Part Number 0340813003 Part Weight 0.367G

Part Name MX150 RCPT 0.3 CABLE GOLD 16AWG D WIND

# **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MX150 RCPT 0.3 CABLE GOLD 16AWG D WIND	Assembly		100	0.367
MX150 RCPT 0.3 CABLE GOLD 16AWG B WIND	Assembly		100	0.367
MX150 RCPT 0.3 CABLE PREBLANK GOLD DWIND	Assembly		100	0.367
MX150 RCPT 0.3 CABLE PREBLANK WOP B WIND	Component		96.1853	0.353
HSM Copper Unplated	Material		96.1853	0.353
Copper	Substance	7440-50-8	94.3097	0.346116
Nickel	Substance	7440-02-0	0.9619	0.00353
Tin	Substance	7440-31-5	0.8657	0.003177
Phosphorus	Substance	7723-14-0	0.0481	0.000177
Gold Plating	Material		0.3815	0.0014
Cobalt	Substance	7440-48-4	0.001	0.000003
Nickel	Substance	7440-02-0	0.001	0.000003
Gold	Substance	7440-57-5	0.3796	0.001393

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Tin Plating	Material		1.9074	0.007
Tin	Substance	7440-31-5	1.9074	0.007
Nickel Plating	Material		1.5259	0.0056
Nickel	Substance	7440-02-0	1.5257	0.005599
Further Additives, not to declare	Substance	system	0.0002	6E-07

# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

# **Contained Substances Exceeding Threshold**

Not reviewed

### **ROHS Declaration Information**

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

**Exemptions** 

None

# **REACH-SVHC Declaration Information**

**Regulatory Revision** D(2020)9139-DC (19 Jan 2021)

#### **Contained Substances Exceeding Threshold**

None

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# **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

# **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead		*Note	500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	High Copper Alloy (NB109)	*Note	10,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
silver	High Copper Alloy (NB109)	*Note	500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	High Copper Alloy (NB109)	*Note	977,000	Yes

<sup>\*</sup>Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

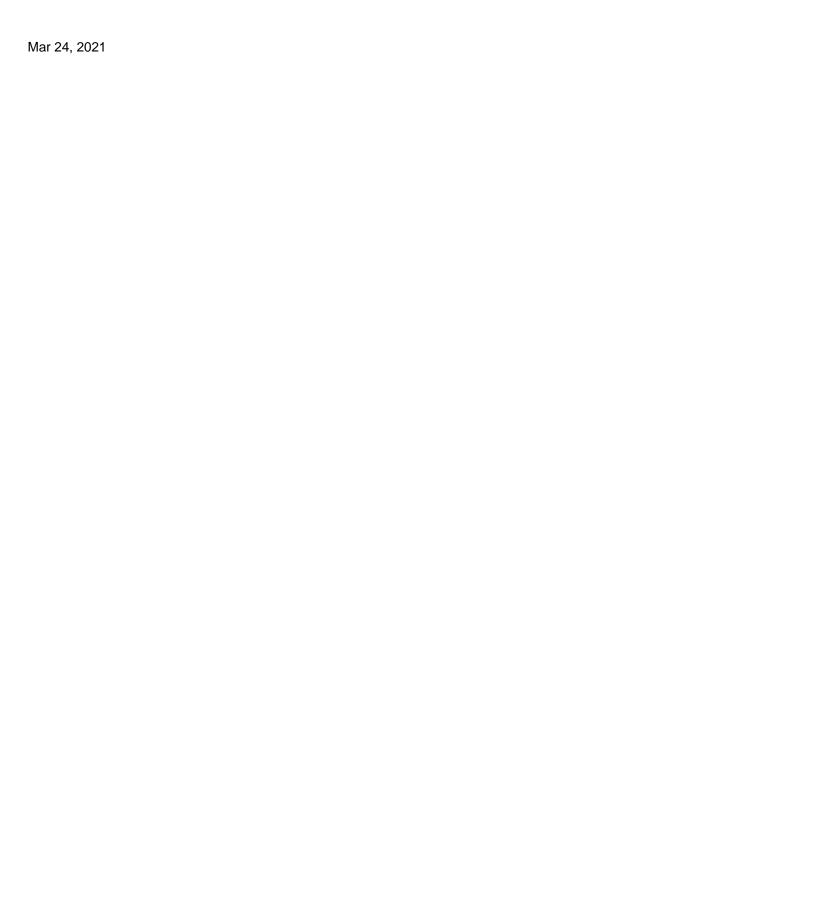
#### **Exemptions**

Part Name	Exemption
	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
High Copper Alloy (NB109)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

#### **Process Information**

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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